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PATENT APPLICATION

ATTORNEY DOCKET NO. 10007457-1

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Jeffrey S. Obert et al

Application No.: 09-888,975

Filing Date: Jun 22, 2001

Title: SLOTTED SUBSTRATE AND SLOTTING PROCESS

Confirmation No.: 23

Examiner: Unassigned

Group Art Unit:

COMMISSIONER FOR PATENTS

Washington, D.C. 20231

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- () Response/Amendment () Petition to extend time to respond
() New fee as calculated below () Supplemental Declaration
() No additional fee (Address envelope to "Box Non-Fee Amendments")
(X) Other: PRELIMINARY AMENDMENT (fee \$ 152)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	30	MINUS	26	= 4	\$ 18	\$ 72
INDEP. CLAIMS	5	MINUS	4	= 1	\$ 80	\$ 80
[] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					\$ 270	\$ 0
EXTENSION FEE	1ST MONTH \$110.00	2ND MONTH \$390.00	3RD MONTH \$890.00	4TH MONTH \$1390.00		\$ 0
OTHER FEES						\$
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 152

Charge \$ 152 to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this sheet is enclosed.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit:

Typed Name: **Lucinda G. Auciello**

Signature: _____

Respectfully submitted,

Jeffrey S. Obert et al

By _____

Lucinda G. Auciello

Attorney Agent for Applicant(s)

Reg. No. **42,270**

Date:

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Patent

**IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE**

Inventors: Jeffrey S. Obert, et al.

Examiner: Unassigned

Serial No: 09/888,975

Group Art Unit: Unassigned

Filing Date: June 22, 2001

Title: Slotted Substrate And Slotting Process

Assistant Commissioner For Patents
Washington DC 20231

PRELIMINARY AMENDMENT

Sir:

Please amend the above-referenced application as follows:

IN THE SPECIFICATION:

Please replace the paragraph starting at Page 4, line 1 with the following paragraph:

--A channel 129, as shown in the embodiment of Fig. 3, is formed as a hole or fluid feed slot through the capping layer 104, and the rest of the thin film stack. The channel 129 fluidically couples the firing chamber 130 and the slot 126, such that fluid flows through the slot 126 and into the firing chamber 130 via channel 129. In one embodiment, entrances to the channels 129 are substantially rectangular and substantially parallel to each other along the capping layer 104, as shown in Fig. 2A. In one embodiment, each channel 129 leads from the slotted substrate to the corresponding firing chamber 130 through the thin film stack. --

Please replace the paragraph starting at Page 4, line 15 with the following paragraphs:

-- In one embodiment shown in Fig. 3, the slot 126 is formed after the thin film stack is deposited on the front side of the substrate. After the thin film layers 104, 107, 108, 110, 111 are formed, then the slot 126 is etched, as shown in Fig. 3. After the slot is formed, the layer 112 is then formed thereover.

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